

## **Rochester Electronics Manufactured Components**

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

## **Quality Overview**

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
  - Class Q Military
  - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

• Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

#### SN5410, SN54LS10, SN54S10, SN7410, SN74LS10, SN74S10 TRIPLE 3-INPUT POSITIVE-NAND GATES SDLS035A – DECEMBER 1983 – REVISED APRIL 2003

- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

#### description

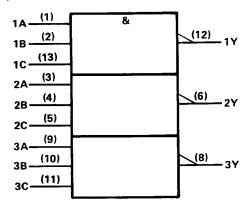
These devices contain three independent 3-input NAND gates.

The SN5410, SN54LS10, and SN54S10 are characterized for operation over the full military temperature range of -55 °C to 125 °C. The SN7410, SN74LS10, and SN74S10 are characterized for operation from 0 °C to 70 °C.

FUNCTION TABLE	(each gate)
----------------	-------------

11	NPUT	OUTPUT	
A	В	С	Y
н	н	н	L
L	х	x	н
x	L	_ x	н
x	х	L	н

#### logic symbol<sup>†</sup>



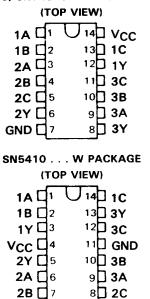
<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, and N packages.

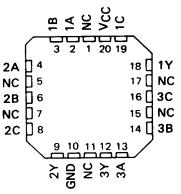
#### positive logic

$$Y = \overline{A \cdot B \cdot C}$$
 or  $Y = \overline{A} + \overline{B} + \overline{C}$ 

SN5410 ... J PACKAGE SN54LS10, SN54S10 ... J OR W PACKAGE SN7410 ... N PACKAGE SN74LS10, SN74S10 ... D OR N PACKAGE

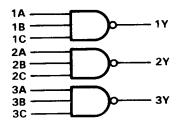


SN54LS10, SN54S10 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

#### logic diagram (positive logic)



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas instruments standard warranty. Production processing does not necessarily include testing of all parameters.

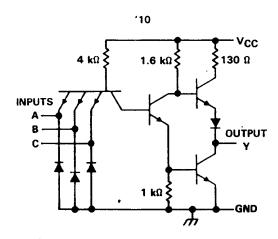


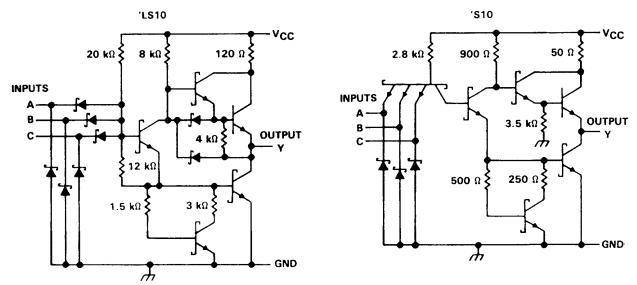
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## SN5410, SN54LS10, SN54S10, SN7410, SN74LS10, SN74S10 TRIPLE 3-INPUT POSITIVE-NAND GATES

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#### schematics (each gate)





Resistor values shown are nominal.

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		
Input voltage: '10, 'S10		<b>5.5</b> V
′LS10		7 V
Operating free-air temperature range:	SN54'	–55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

## recommended operating conditions

		SN5410			SN7410		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V <sub>CC</sub> Supply voltage	4.5	5	5.5	4.75	5	5.25	v
VIH High-level input voltage	2			2			v
VIL Low-level input voltage			0.8			0.8	v
IOH High-level output current			- 0.4			- 0.4	mA
IOL Low-level output current			16			. 16	mA
T <sub>A</sub> Operating free-air temperature	- 55		125	0		70	°c

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS T		SN5410						
			MIN	түр‡	МАХ	MIN	TYP‡	MAX	
VIK	V <sub>CC</sub> = MIN, I <sub>I</sub> = - 12 mA				- 1.5			- 1.5	v
v <sub>он</sub>	V <sub>CC</sub> = MIN, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> =	0.4 mA	2.4	3.4		2.4	3.4		v
VOL	V <sub>CC</sub> = MIN, V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 1	16 mA		0.2	0.4		0.2	0.4	v
1	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V				1			1	mA
Чн	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.4 V				40			40	μA
11L	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.4 V				- 1.6			- 1.6	mA
1 <sub>OS</sub> §	V <sub>CC</sub> = MAX		- 20		- 55	- 18		- 55	mA
ICCH	V <sub>CC</sub> = MAX, V <sub>1</sub> = 0 V			3	6		3	6	mA
ICCL	V <sub>CC</sub> = MAX, V <sub>1</sub> = 4.5 V			9	16.5		9	16.5	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> =  $25^{\circ}$ C.

§ Not more than one output should be shorted at a time.

### switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM TO						
FARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS		ТҮР	MAX	UNIT
<sup>t</sup> PLH				1	11	22	ns
<sup>t</sup> PHL	A, B or C	Ŷ	R <sub>L</sub> <b>= 400</b> Ω, C <sub>L</sub> = 15 pF		7	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



# SN54LS10, SN74LS10, TRIPLE 3-INPUT POSITIVE-NAND GATES

SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

#### recommended operating conditions

		SN54LS10		SN74LS10			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC Supply voltage	4.5	5	5.5	4.75	5	5.25	v
VIH High-level input voltage	2			2			v
VIL Low-level input voltage			0.7			0.8	v
IOH High-level output current			- 0.4		·	- 0.4	mA
IOL Low-level output current			4	<u> </u>		8	mA
T <sub>A</sub> Operating free-air temperature	- 55		125	0		70	°C

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS \$			SN54LS10			SN74LS10			
FARAMETER		TEST CONDIT	IDITIONS I		TYP‡	MAX	MIN	TYP‡	MAX	UNIT
۷IK	V <sub>CC</sub> = MIN,	l <sub>l</sub> = – 18 mA				- 1.5			- 1.5	V
V <sub>OH</sub>	V <sub>CC</sub> = MIN,	VIL = MAX,	l <sub>OH</sub> = 0.4 mA	2.5	3.4		2.7	3.4		V
N.e.	V <sub>CC</sub> = MIN,	V <sub>IH</sub> = 2 V,	1 <sub>OL</sub> = 4 mA		0.25	0.4	[		0.4	v
VOL	V <sub>CC</sub> = MIN,	V <sub>1H</sub> = 2 V,	IOL = 8 mA					0.25	0.5	1
i <sub>l</sub>	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 7 V				0.1			0.1	mA
ίн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 2.7 V				20			20	μΑ
ίιL	V <sub>CC</sub> = MAX,	V1 = 0.4 V				- 0.4			- 0.4	mA
los§	V <sub>CC</sub> = MAX			- 20		- 100	- 20		- 100	mA
Іссн	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 0 V			0.6	1.2	1	0.6	1.2	mA
ICCL	V <sub>CC</sub> = MAX,	V <sub>1</sub> = 4.5 V			1.8	3.3		1.8	3.3	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ . § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

## switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDI	TIONS	MIN	түр	мах	UNIT
tPLH	A, B or C	Y	$R_1 = 2 k\Omega_2$	C <sub>1</sub> = 15 pF		9	15	ns
<sup>t</sup> PHL			n[ - 2 kst,	с <u>с</u> – 15 рг		10	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



SDLS035 - DECEMBER 1983 - REVISED MARCH 1988

#### recommended operating conditions

			SN54S10			SN74S10			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	v	
v <sub>ін</sub>	High-level input voltage	2			2			v	
VIL	Low-level input voltage			0.8			0.8	v	
юн	High-level output current			- 1			- 1	mA	
IOL	Low-level output current			20			20	mA	
TA	Operating free-air temperature	- 55		125	0		70	°C	

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN54S10	SN74S10	UNIT
PARAMETER	TEST CONDITIONS †	MIN TYP‡ MAX	MIN TYP‡ MAX	
VIK	V <sub>CC</sub> = MIN, I <sub>I</sub> = -18 mA	-1.2	-1.2	v
V <sub>OH</sub>	V <sub>CC</sub> ≈ MIN, V <sub>IL</sub> = 0.8 V, I <sub>OH</sub> = −1 mA	2.5 3.4	2.7 3.4	~
VOL	$V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 20 mA$	0.5	0.5	v
l)	V <sub>CC</sub> = MAX, V <sub>I</sub> = 5.5 V	1	1	mA
Ιн	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V	50	50	μA
ήL	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5 V	-2	-2	mA
IOS §	V <sub>CC</sub> = MAX	-40 -100	-40 -100	mA
ICCH	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0 V	7.5 12	7.5 12	mA
ICCL	V <sub>CC</sub> = MAX, V <sub>I</sub> = 4.5 V	15 27	15 27	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at  $V_{CC} = 5 V$ ,  $T_A = 25^{\circ}C$ . § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

#### FROM то PARAMETER **TEST CONDITIONS** MIN ТҮР MAX UNIT (INPUT) (OUTPUT) 3 **tPLH** 4.5 ns $R_L = 280 \Omega$ , C<sub>L</sub> = 15 pF **tPHL** 3 5 ns A, B or C Y 4.5 <sup>t</sup>PLH ns $R_L = 280 \Omega$ , CL = 50 pF 5 <sup>t</sup>PHL ns

### switching characteristics, $V_{CC} = 5 V$ , $T_A = 25^{\circ}C$ (see note 2)

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



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Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

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18-Sep-2008

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	n MSL Peak Temp <sup>(3)</sup>
JM38510/00103BCA	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
JM38510/00103BDA	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
JM38510/07005BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/07005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30005B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/30005BCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30005BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/30005SCA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/30005SDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN5410J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN54LS10J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54S10J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN7410N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN7410N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN7410NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS10D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS10N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74LS10NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS10NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS10NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10N	ACTIVE	PDIP	Ν	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
						(RoHS)		
SN74S10N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74S10NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74S10NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S10NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ5410J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ5410W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI
SNJ5410WA	OBSOLETE	CFP	WA	14		TBD	Call TI	Call TI
SNJ54LS10FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS10J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54S10FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54S10J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54S10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*Al	dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74LS10DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74LS10NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
	SN74S10NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



## PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS10DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LS10NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74S10NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

#### MECHANICAL DATA

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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#### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.



## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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